RESPONSE UNDER 37 CFR 1.116 **EXPEDITED PROCEDURE EXAMINING GROUP 2811**

PATENT APPLICATION

Docket No.: 9898-208

Client Ref. No.: SS-15400-US-RCE-RCE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Ki-Won CHOI

Serial No.:

10/055,266

Examiner:

Nadav, Ori

Filed:

January 22, 2002

Group Art Unit:

2811

Confirmation No.:

6747

For:

SEMICONDUCTOR PACKAGE HAVING CHANGED SUBSTRATE

DESIGN USING SPECIAL WIRE BONDING

Date:

January 10, 2007

Mail Stop AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116

Responsive to the Final Office Action, Paper No. 20061001, dated October 11, 2006, please amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Drawings begin on page 3 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 of this paper.

Remarks/Arguments begin on page 7 of this paper.

An Appendix including amended drawing figures is attached following page 10 of this paper.

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